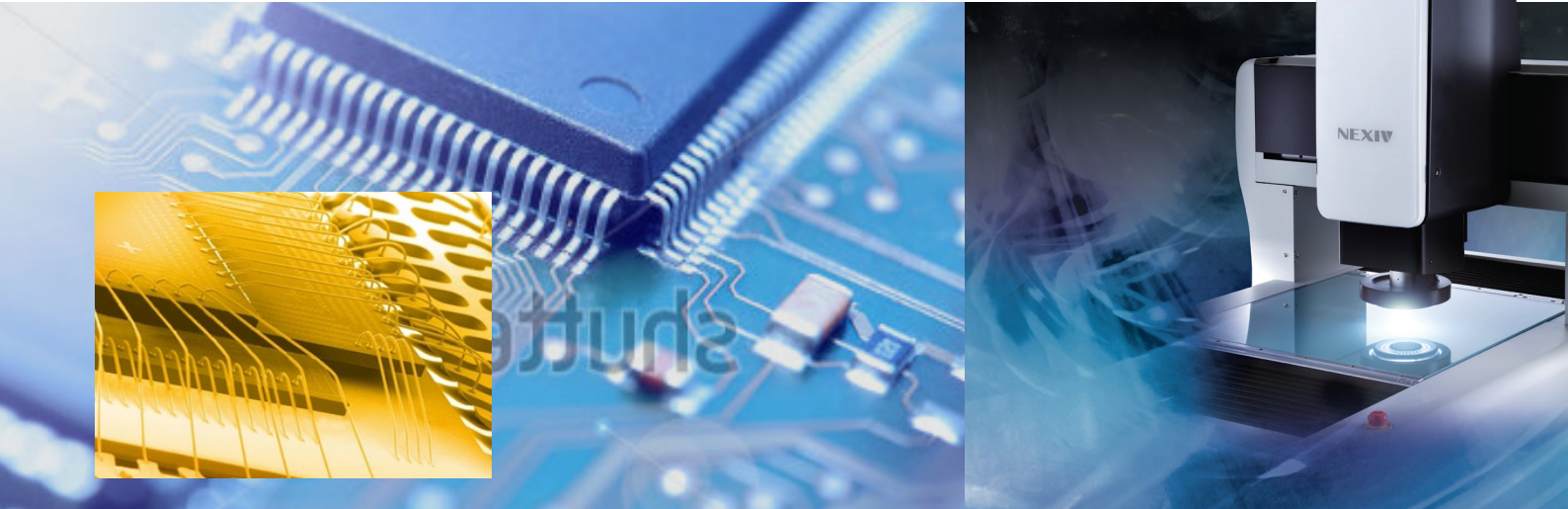




## ApplicationFocus PCB Loop height



# Inspection and Measurement of Wire Bond Loop Height

Wire bonding is the method of making interconnections between an integrated circuit (IC) or other semiconductor device and its packaging during semiconductor device fabrication.

Controlling the Loop Height of a wire bond is very important and requires accurate measurement to guarantee device integrity.

In order to increase yield, height defects must be detected early in the production cycle by high speed automated measurement.

Typically it is very difficult to achieve fully automated measurements because of the complexity of this feature. But NEXIV overcomes these difficulties by various capabilities.

### System Challenge

Only NEXIV has following capability:

- Find complex loop position automatically
- Measure highest loop position automatically
- Generate feedback for process improvement

### Nikon's Solution

NEXIV VMZ-R3020 with Automeasure Software

- Search capability for finding complex loop
- Multi vision focus for irregular and complex loop height
- Generate quantitative data for statistical process control
- Measure multiple samples with faster throughput

CNC Video Measuring Systems

**NEXIV**

